



FDP3651U

N-Channel PowerTrench[®] MOSFET

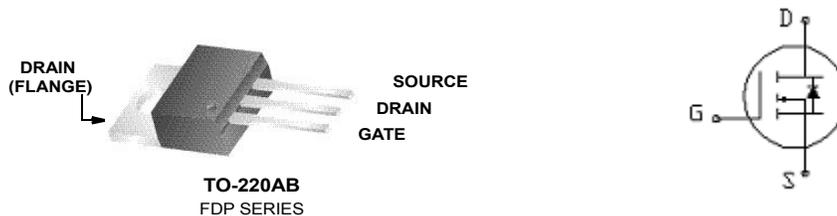
100V, 80A, 15mΩ

Features

- $r_{DS(on)}=13\text{ m}\Omega(\text{Typ.}), V_{GS} = 10\text{V}, I_D = 40\text{A}$
- $Q_{g(TOT)}=49\text{ nc}(\text{Typ.}), V_{GS} = 10\text{ V}$
- Low Miller Charge
- Low Q_{rr} Body Diode
- UIS Capability (Single Pulse/Repetitive Pulse)

Applications

- DC/DC converters and Off-Line UPS
- Distributed Power Architectures and VRMs
- Primary Switch for 24V and 48V Systems
- High Voltage Synchronous Rectifier



MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain to Source Voltage	100	V
V_{GSS}	Gate to Source Voltage	± 20	V
I_D	Drain Current -Continuous	80	A
	-Pulsed (Note 1)	220	
P_D	Power Dissipation	255	W
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	266	mJ
T_J, T_{STG}	Operating and Storage Temperature	-55 to 175	$^\circ\text{C}$
T_L	Maximum lead temperature soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance , Junction to Ambient	62	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance , Junction to Case	0.59	$^\circ\text{C/W}$

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape Width	Quantity
FDP3651U	FDP3651U	Tube	N/A	50 units

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
--------	-----------	-----------------	-----	-----	-----	-------

Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	100	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 80\text{V}$ $V_{GS} = 0\text{V}$	-	-	1	μA
		$T_C = 150^\circ\text{C}$	-	-	250	μA
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20\text{V}$	-	-	± 100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = -250\mu\text{A}$	3.5	4.5	5.5	V
$r_{DS(on)}$	Drain to Source On Resistance	$V_{GS} = 10\text{V}, I_D = 80\text{A}$	-	15	18	m Ω
		$V_{GS} = 10\text{V}, I_D = 40\text{A}$	-	13	15	
		$V_{GS} = 10\text{V}, I_D = 40\text{A}, T_J = 175^\circ\text{C}$	-	32	37	

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}$ $f = 1\text{MHz}$	-	4152	5522	pF	
C_{oss}	Output Capacitance		-	485	728	pF	
C_{rss}	Reverse Transfer Capacitance		-	89	118	pF	
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0\text{V to } 10\text{V}$	$V_{DD} = 50\text{V}$ $I_D = 80\text{A}$	-	49	69	nC
$Q_{g(TH)}$	Threshold Gate Charge	$V_{GS} = 0\text{V to } 2\text{V}$		-	7	9.8	nC
Q_{gs}	Gate to Source Gate Charge			-	23	-	nC
Q_{gd}	Gate to Drain Charge			-	16	-	nC

Resistive Switching Characteristics

$t_{(on)}$	Turn-On Time	$V_{DD} = 50\text{V}, I_D = 80\text{A}$ $V_{GS} = 10\text{V}, R_{GS} = 5.0\Omega$	-	-	64	ns
$t_{d(on)}$	Turn-On Delay Time		-	15	27	ns
t_r	Rise Time		-	16	29	ns
$t_{d(off)}$	Turn-Off Delay Time		-	32	52	ns
t_f	Fall Time		-	14	26	ns
$t_{(off)}$	Turn-Off Time		-	-	78	ns

Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Forward Voltage	$I_{SD} = 80\text{A}$	-	0.99	1.25	V
		$I_{SD} = 40\text{A}$	-	0.88	1.0	V
t_{rr}	Reverse Recovery Time	$I_S = 40\text{A}, di/dt = 100\text{A}/\mu\text{s}$	-	70	105	ns
Q_{rr}	Reverse Recovery Charge		-	202	303	nC

Notes:

1. Pulse Test: Pulse Width < 300 μs , Duty Cycle < 2.0%
2. $L = 0.13\text{mH}, I_{AS} = 64\text{A}, V_{DD} = 50\text{V}, R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

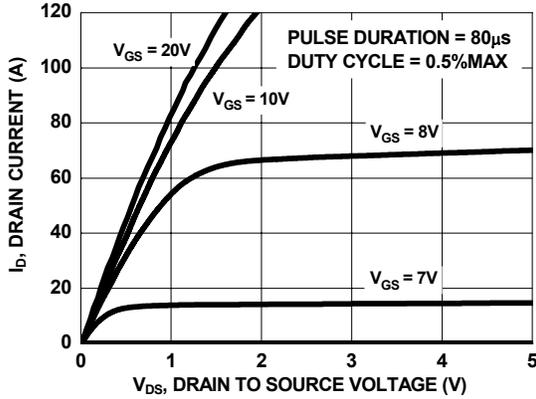


Figure 1. On Region Characteristics

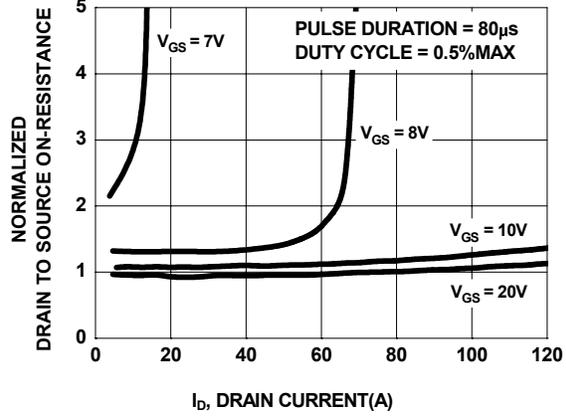


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

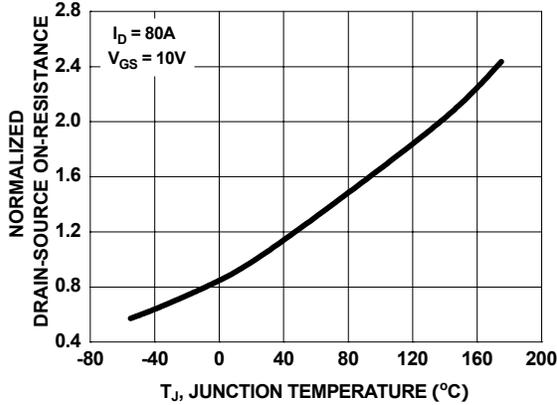


Figure 3. Normalized On Resistance vs Junction Temperature

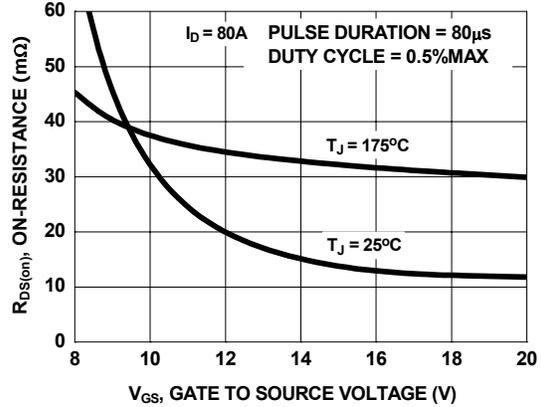


Figure 4. On-Resistance vs Gate to Source Voltage

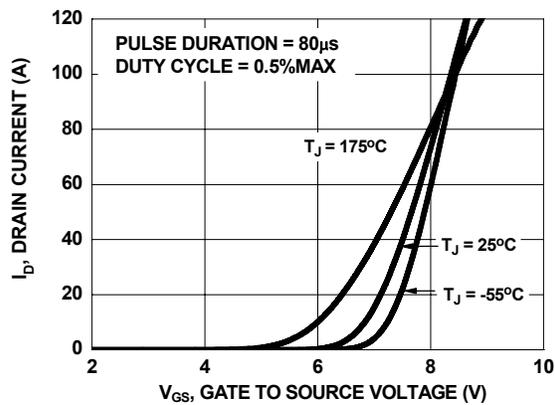


Figure 5. Transfer Characteristics

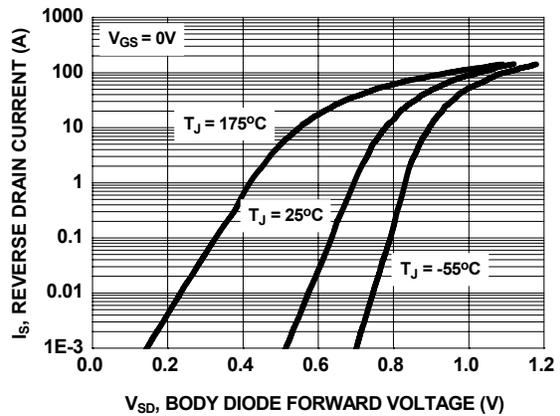


Figure 6. Source to Drain Diode Forward Voltage vs Source Current